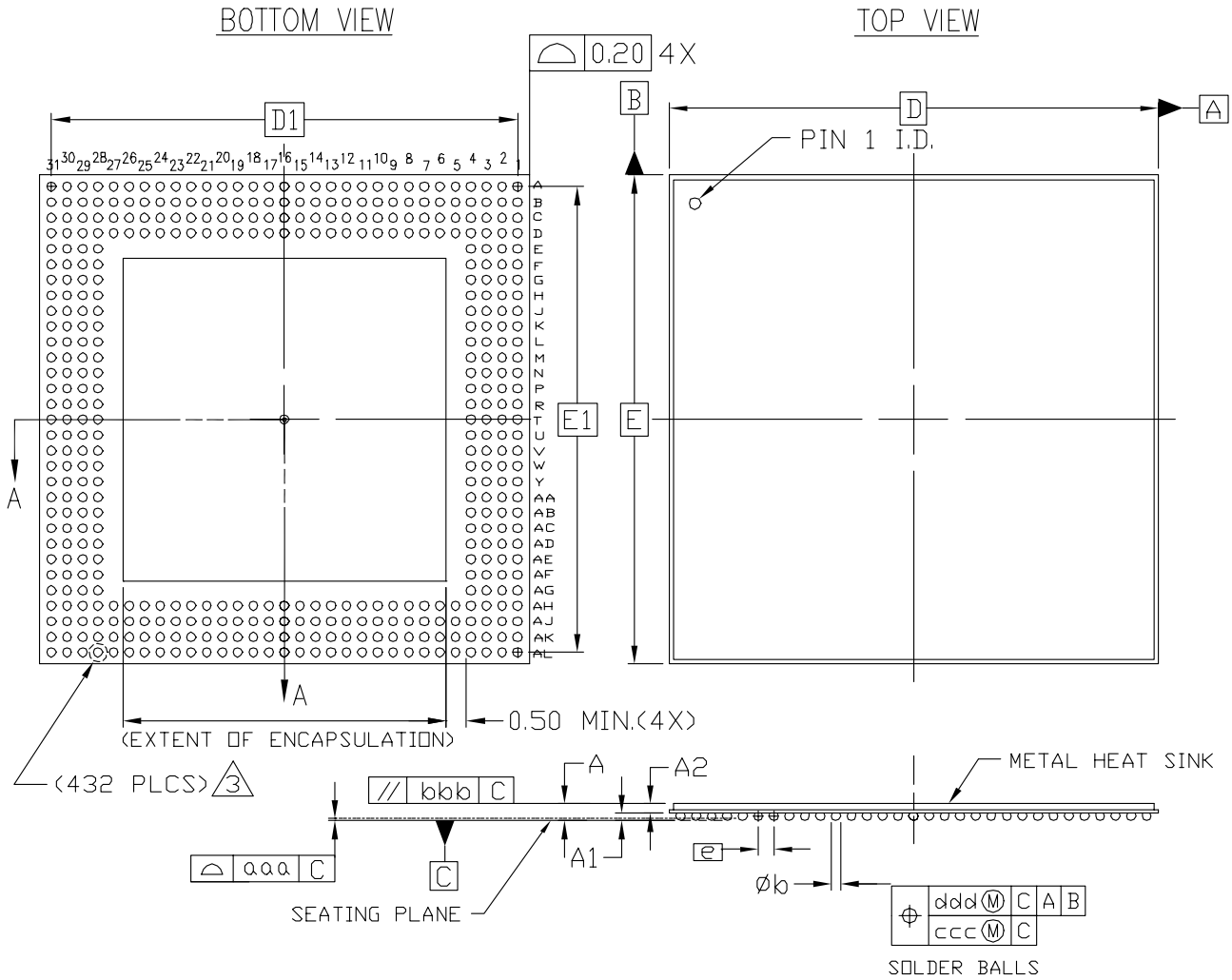
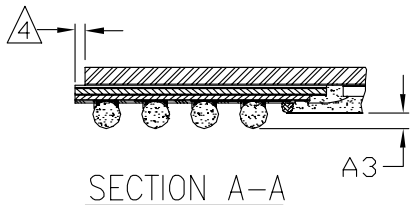
Metal BGA (BG432) — Cavity Down Package



SYMBOL	MILLIMETERS			NOTE
	MIN.	NOM.	MAX.	
A		1.40	1.70	
A_1	0.50	0.60		
A_2	0.60		1.10	
A_3	0.20			
D/E	40.00 BSC			
D_1/E_1	38.10 REF.			
e	1.27 BSC			
øb	0.60	0.75	0.90	
aaa			0.20	
bbb			0.25	
ccc			0.15	
ddd			0.30	
M	31			2
REF.	JEDEC MO-192-BAU-1			



SECTION A–A
(NOT TO SCALE)

NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M–1994
2. SYMBOL "M" IS THE PIN MATRIX SIZE.
3. LAND PAD OPENING – SOLDER MASK DEFINED ø0.615mm (0.024")
4. HEAT SINK PULLBACK – 0.375mm MAX.

432–BALL METAL BGA (BG432) – CAVITY DOWN

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